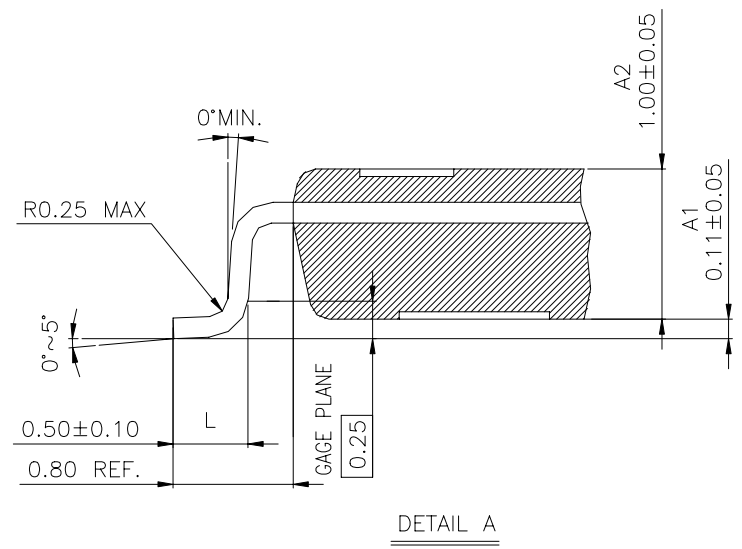
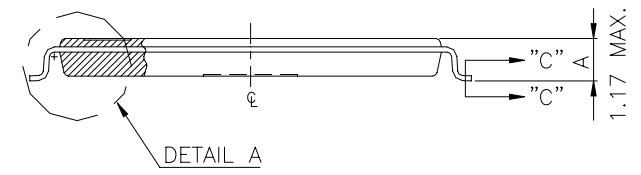
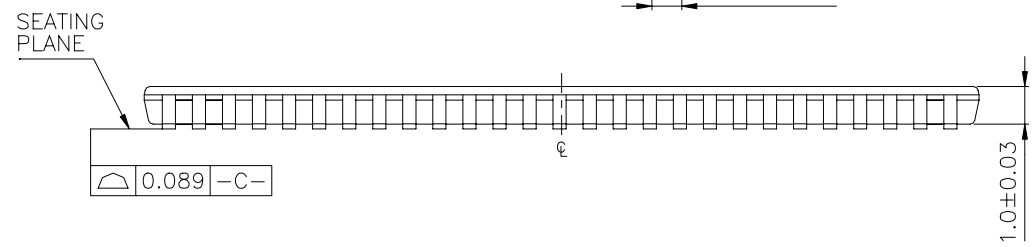


NOTES:

1. ALL DIMENSIONS ARE IN MM.
2. DIMENSION D1 AND E1 DOES NOT INCLUDE MOLD PROTRUSION.
3. COPLANARITY OF ALL LEADS SHALL BE 3.5 MILS MAX. (BEFORE TEST) UNLESS OTHERWISE SPECIFIED.
4. GENERAL PHYSICAL OUTLINE SPEC IS REFER TO TMC'S FINAL VISUAL INSPECTION SPEC UNLESS OTHERWISE SPECIFIED.
5. PLATING THICKNESS 0.200~0.800 MILS.



3		
2		
1		
REV.	DESCRIPTION OF REVISION	SIGNATURE/DATE
<b>晶揚科技股份有限公司</b> <b>Taiwan Micropaq Corporation</b>		TITLE TSOP 54 LOC PACKAGE OUTLINE DWG.
DWG. NO. EOL-S0540400-001 R0		FILE S54400001
DESIGNER 胡淑貞	DATE 04/30/98	MATERIAL
CHECKER	DATE	PROCESSES
APPROVED	DATE	UNIT MM
SCALE 5:1		SHEET NO. 1 OF 1
		THIRD ANGLE PROJECTION ALL DIMENSIONS IN MILLIMETERS.